



## Final Product Change Notification

201506032F01

**Issue Date:** 05-Aug-2015

**Effective Date:** 16-Nov-2015

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# QUALITY

### Management Summary

Introduction SO8 reduced diepad at ASEN.

#### Change Category

<input type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

## SO8 reduced diepad at ASEN

### Details of this Change

Diepad size will be reduced from 2.1mm x 2.1mm to 1.65mm x 1.65mm.

#### Why do we Implement this Change

Standardization of the backend part of the assembly manufacturing process.

#### Identification of Affected Products

Product identification does not change

Remark: change is clearly visible based on X-Ray (small diepad).

### Product Availability

#### Sample Information

Samples are available upon request

#### Production

Planned first shipment 17-Nov-2015

### Impact

no impact to the product's functionality anticipated.

#### Data Sheet Revision

No impact to existing datasheet

#### Disposition of Old Products

Existing inventory will be shipped until depleted

### Additional information

Affected products and sales history information: see attached file

Self qualification: view online

### Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 04-Sep-2015.

#### Remarks

n.a.

#### Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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